			T				
APPLIC <i>A</i>	ABLE STAN	IDARD					
OPERATING TEMPERATURE		RE RANGE	-35 °C TO +85°C (NOTE1)	STORAGE TEMPERATURE RANGE -10 °C TO +60°C (OTE3)	
RATING	OPERATING HUMIDITY RANGE VOLTAGE		40% TO 80% (NOTE2)	STORAGE HUMIDITY RANGE	UMIDITY RANGE 40% TO 70% (NO		
			100 V AC/DC	APPLICABLE DF19#-*P-1H(## CONNECTOR DF19-*P-1V(## APPLICABLE THIN COAXIAL CA			
		36AWG : 0.5A/pin					BLE
CURRENT		40AWG : 0.3A/pin		CABLE 36AWG, 40AWG		}	
			SPECIFICAT	IONS			
ľ	TEM		TEST METHOD	1	IREMENTS	QT	АТ
CONST	RUCTION			•			
GENERAL EX		VISUALLY	AND BY MEASURING INSTRUMENT.	ACCORDING TO DRAWIN	NG.	Х	Х
MARKING		CONFIRMED VISUALLY.		1		X	X
ELECTR	IC CHARA	CTERIS	STICS			1	
CONTACT RESISTANCE		100 mA (DC OR 1000Hz)		80mΩ ΜΑΧ.		Х	_
INSULATION	RESISTANCE	100 V DC.		500 MΩ MIN.		X	_
VOLTAGE PF	ROOF	300 V AC FOR 1 min.		NO FLASHOVER OR BREAKDOWN.		X	_
MECHAI	NICAL CHA	ARACTE	FRISTICS				
	L OPERATION		INSERTIONS AND EXTRACTIONS.	1) CONTACT RESITANCE	:.		
INECTIANICAL OF EXATION				NO VARIATION OF 50mΩ OR MORE FROM INITIAL VALUE. 2) NO DAMAGE, CRACK OR LOOSENESS OF PARTS.			_
VIBRATION		FREQUENCY 10 TO 55 Hz, SINGLE AMPLITUDE 0.75 mm, AT 2h FOR 3 DIRECTION.		1) ELECTRICAL DISCONTINUITY OF 1 µs. 2) NO DAMAGE, CRACK OR LOOSENESS OF PARTS.			_
SHOCK		490 m/s ² DURATION OF PULSE 11 ms AT 3 TIMES					_
EN1/400			RECTIONS.			Х	
			ACTERISTICS	T.,,			
DAMP HEAT(STEADY STATE)		EXPOSED AT 40±2°C , 90 TO 95 %, 96 h. (AFTER LEAVING THE ROOM TEMPERATURE FOR 1		1) CONTACT RESITANCE:		X	_
		TO 2h.)	EAVING THE ROOM TEMPERATURE FOR	NO VARIATION OF $50 \text{m}\Omega$ OR MORE FROM INITIAL VALUE. 2) INSULATION RESISTANCE: $500 \text{ M}\Omega$ MIN.			
		10 211.)			OR LOOSENESS OF PARTS.		
RAPID CHAN	IGE OF	TEMPERA	ATURE -55°C→ +85°C	1) CONTACT RESITANCE			
TEMPERATURE		TIME	30min→ 30min	NO VARIATION OF 50mΩ C	OR MORE FROM INITIAL VALUE.		
		UNDER 5	CYCLES.	2) INSULATION RESISTANCE: 500 M Ω MIN.			İ
		(THE TRA	NSFERRING TIME OF THE TANK IS	3) NO DAMAGE, CRACK (OR LOOSENESS OF PARTS.	X	_
		2 TO 3 mi	,				
			EAVING THE ROOM TEMPERATURE FOR	1			
RESISTANCE	= TO	TO 2h.)	MENDED TEMPERATURE PROFILE]	NO DEFORMATION OF C	ASE OF EXCESSIVE	+	
RESISTANCE TO SOLDERING HEAT		_	TEMPERATURE, 260°C	NO DEFORMATION OF CASE OF EXCESSIVE LOOSENESS OF THE TERMINALS.			
			MERSION, DURATION, 10s		·	X	-
SOLDERABIL	_ITY	SOLDER	ING TEMPERATURE : 245°C	A NEW UNIFORM COATIN	NG OF SOLDER SHALL		
		DURATIO	ON OF IMMERSION : SOLDERING, FOR 2s	COVER MINIMUM OF 95% IMMERSED.	6 OF THE SURFACE BEING	Х	_
REMARKS							

NOTE 1: INCLUDE THE TEMPERATURE RISING BY CURRENT.

NOTE2: NO CONDENSING

NOTE3: APPLY TO THE CONDITION OF LONG TERM STORAGE FOR UNUSED PRODUCTS BEFORE MOUNTED ON PCB. AFTER MOUNTED ON PCB, OPERATING TEMPERATURE AND HUMIDITTY RANGE IS APPLIED FOR INTERIM STRAGE DURING TRANSPORTATION.

COU	NT DESCRIPTION OF REVISIONS	DESIGNED		CHECKED	DAT	ſΕ
\triangle						
			APPROVED	HS. OKAWA	20200	313
			CHECKED	TS. KUMAZAWA	20200	313
Unless of	erwise specified, refer to IEC 60512.		DESIGNED	HK. HAYASHI	20200	313
			DRAWN	DS. HIROWATARI	20200	306
Note QT:	Qualification Test AT: Assurance Test X:Applicable Test	DRAWIN	DRAWING NO. ELC-306221		-06-00	
HS.	SPECIFICATION SHEET	PART NO.	DF19G-*S-1SD (06))	
	HIROSE ELECTRIC CO., LTD.	CODE NO.	CL685		<u>A</u> 1	1/1